

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1460GIZ-2.5#PBF

(Engineering Calculation)

TO-92

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TOTAL MASS (g):

0.2043872

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001361	1000000	6658.93		
Die Coat	Dow Corning	Silicone	67762-90-7	7.6E-05	1000000	371.8432		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.088433	975000	432673.8		
		Iron (Fe)	7439-89-6	0.002177	24000	10651.35		
		Phosphorus (P)	7723-14-0	2.7E-05	300	132.1022		
		Zinc (Zn)	7440-66-6	6.3E-05	700	308.2385		
		Nickel (Ni)	7440-02-0	0	0	0		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead Frame Total:				0.0907	1000000	443765.6
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.0056802	1000000	27791.37		
		External Plating Total:				0.0056802	1000000	27791.37
		Inter. Plating Ni	7440-02-0	0	0	0		
		Inter. Plating Ag	7440-22-4	0.00032	1000000	1565.656		
		Internal Plating Total:				0.00032	1000000	1565.656
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.00054	750000	2642.044		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead (Pb)	7439-92-1	0	0	0		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Resin (EP)		0.00018	250000	880.6814		
Die Attach Total:				0.00072	1000000	3522.726		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.025294	240000	123755.3		
		Bromine (Br)	40039-93-8	0.001054	10000	5156.878		
		Silica (SiO2)	60676-86-0	0.075881	720000	371261		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.003162	30000	15470.64		
		Metal Hydroxid		0	0	0		
		Carbon Black (C)	1333-86-4	0	0	0		
		Encapsulation Total:				0.105391	1000000	515643.8
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000139	1000000	680.0817		